

10 9 8 7 6 5 4 3 2 1

NOTES :

1. MATERIAL :

HOUSING : (a) HIGH TEMP. NYLON ,GLASS FIBER FILLED,UL94V-O, COLOR: BLACK,
(b) POLYESTER , GLASS FIBER FILLED,UL94V-O, COLOR: WHITE,

TERMINAL : PHOSPHOR BRONZE
METAL SHELL : COPPER ALLOY

2. PLATING :

TERMINAL :

CONTACT AREA : (a) GOLD FLASH.

(b) GLOD (Au), THICKNESS = 30 MICROINCH MINIMUM.
/0.76 MICROMETER MINIMUM.

SOLDER TAIL :

PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM .
/1.9 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.

METAL SHELL :

PURE TIN(Sn) , THICKNESS= 50 MICROINCH MINIMUM.
/1.27 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni) , THICKNESS= 50 MICROINCH MINIMUM.

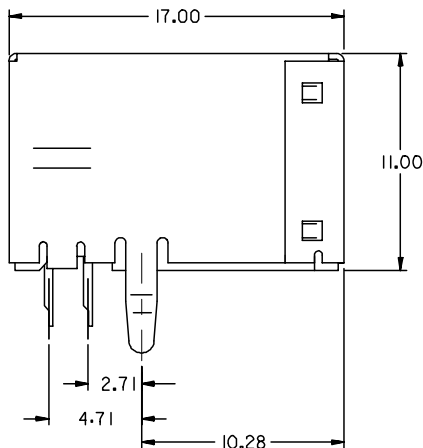
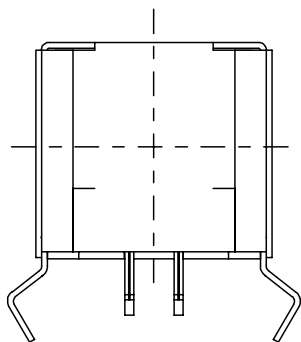
/1.27 MICROMETER MINIMUM.

3 DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER

RECOMMENDED PCB THICKNESS : 1.60±0.05

4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000

MOLEX ID OF MFG PLANT CODE



PART NUMBER LEGEND:

67068-

8 : BLACK HOUSING

9 : WHITE HOUSING

0 : TRAY PACKAGING

1 : TUBE PACKAGING

0 : GOLD FLASH

1 : 0.76 MICROMETER/30
MICROINCH GOLD

KINK TYPE BOARD LOCK

NEW RELEASE
EC NO: SH2005-0142
DRWN: DAVID HU 2004/11/5
CHKD:HARVEY 2004/11/25
APPR:YTYAP 2004/11/25
REV
A

QUALITY
SYMBOLS

▽=0

▽=0

GENERAL TOLERANCES
(UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.25	± ---
1 PLACE	± 0.25	± ---
ANGULAR ± 3 °		

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY

DRAWN BY	DATE
DAVID HU	2004/11/05
CHECKED BY	DATE
HARVEY	2004/11/05
APPROVED BY	DATE

MATERIAL NO.

SEE NOTES

SCALE
4:1

DESIGN UNITS
METRIC

THIRD ANGLE
PROJECTION

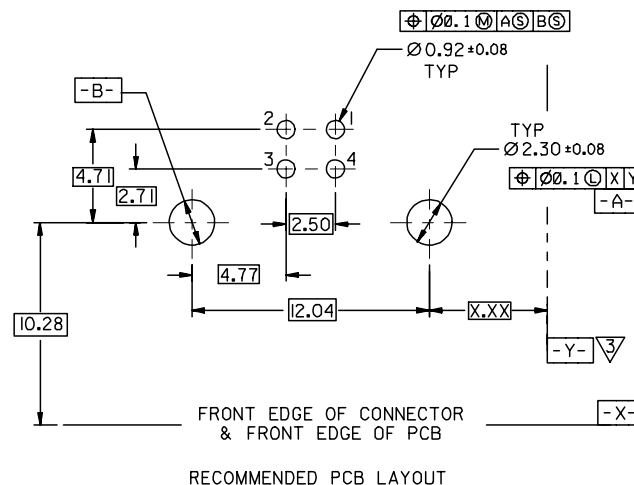
TITLE
USB B TYPE CONNECTOR
KINK TYPE BOARD LOCK
(LEAD-FREE)

MOLEX INCORPORATED

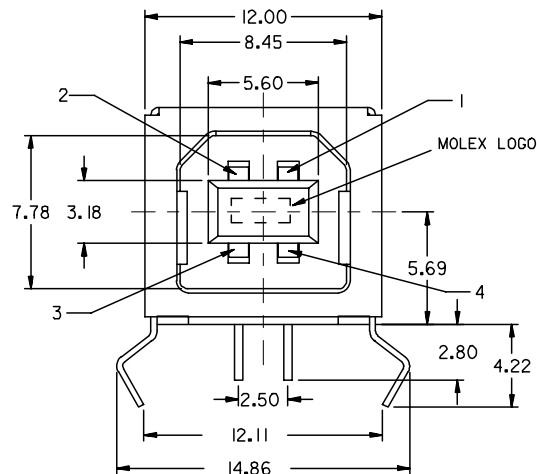
DOCUMENT NO.

SD-67068-003

SHEET NO.
1 OF 4



RECOMMENDED PCB LAYOUT



10 9 8 7 6 5 4 3 2 1

NOTES :

1. MATERIAL :

HOUSING : (a) HIGH TEMP. NYLON, GLASS FIBER FILLED, UL94V-0, COLOR: BLACK,

(b) POLYESTER, GLASS FIBER FILLED, UL94V-0, COLOR: WHITE,

TERMINAL : PHOSPHOR BRONZE

METAL SHELL : COPPER ALLOY

2. PLATING :

TERMINAL :

CONTACT AREA : (a) GOLD FLASH.

(b) GLOD (Au), THICKNESS = 30 MICROINCH MINIMUM.
/0.76 MICROMETER MINIMUM.

SOLDER TAIL :

PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM .
/1.9 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.

METAL SHELL : /1.27 MICROMETER MINIMUM.

PURE TIN(Sn) THICKNESS= 50 MICROINCH MINIMUM.

/1.27 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.

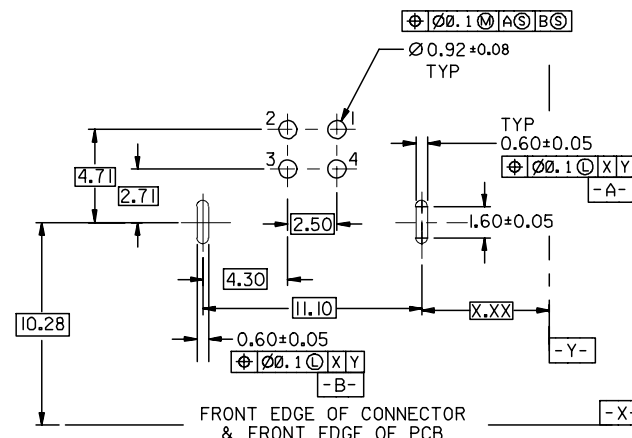
/1.27 MICROMETER MINIMUM.

3 DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER

RECOMMENDED PCB THICKNESS : 1.60±0.05

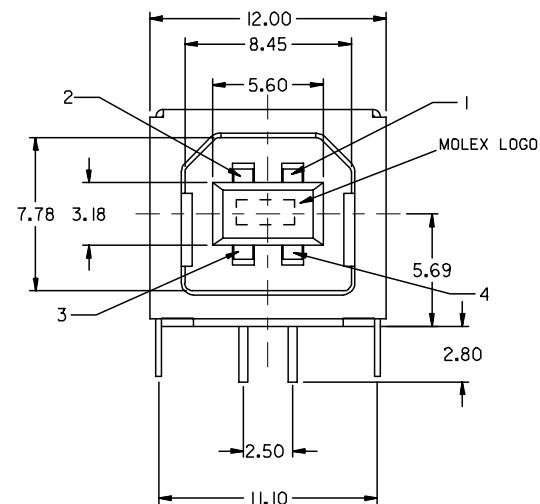
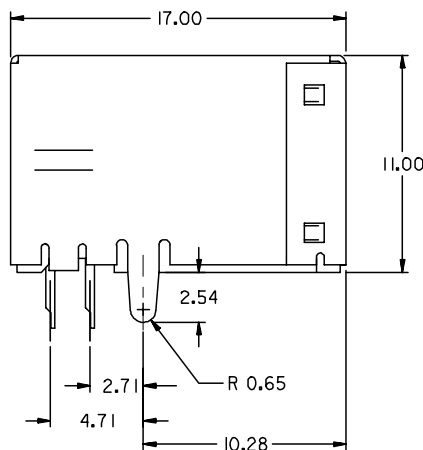
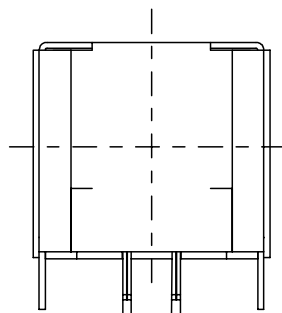
4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000

MOLEX ID OF MFG PLANT CODE



FRONT EDGE OF CONNECTOR
& FRONT EDGE OF PCB

RECOMMENDED PCB LAYOUT



PART NUMBER LEGEND:

67068-

8 : BLACK HOUSING

9 : WHITE HOUSING

0 : TRAY PACKAGING

1 : TUBE PACKAGING

0 : GOLD FLASH

1 : 0.76 MICROMETER/30

MICROINCH GOLD

STRAIGHT TAB

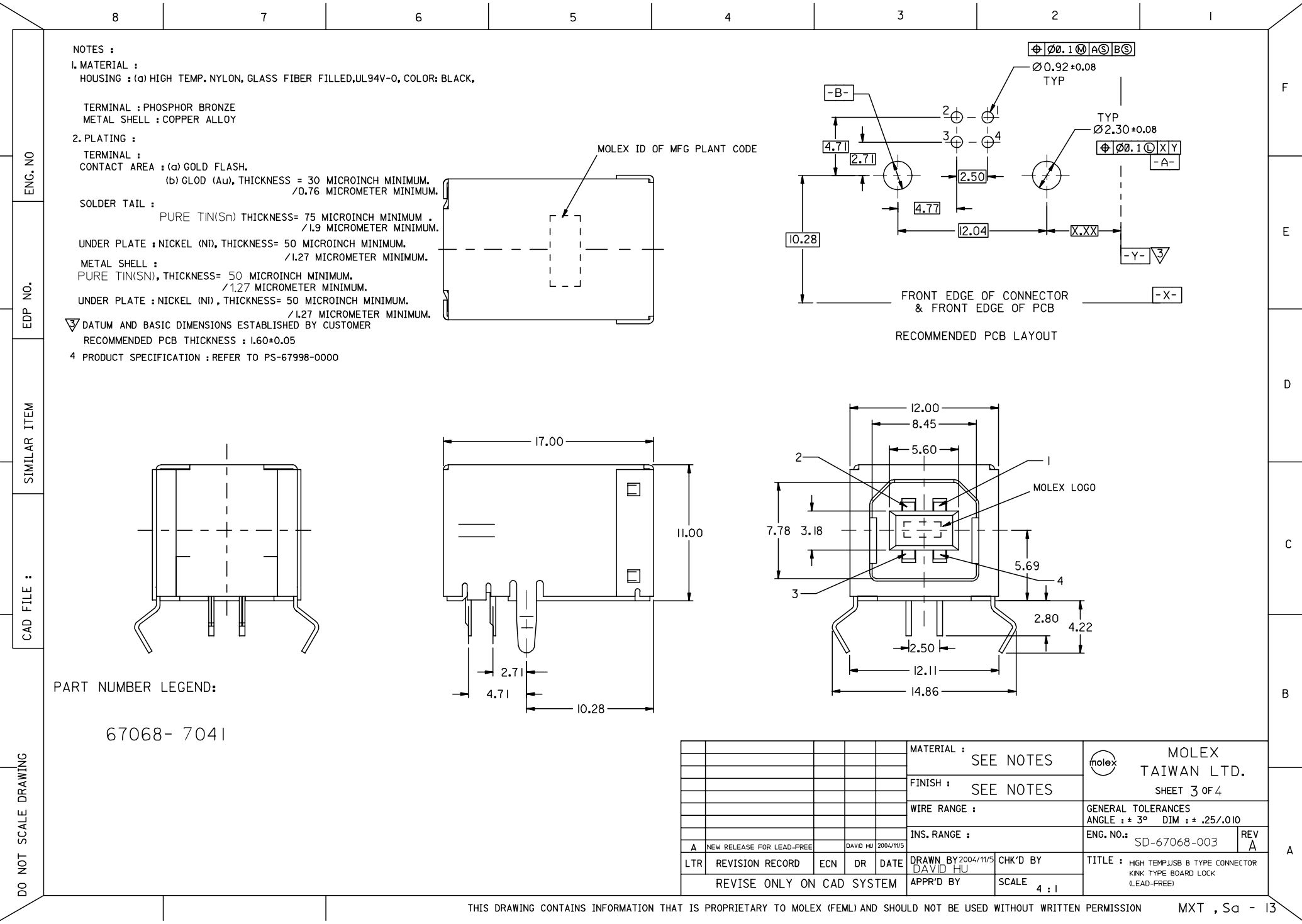
NEW RELEASE	EC NO: SH2005-0142	DRWN: DAVID HU 2004/11/05	CHKD: HARVEY 2004/11/25	APPR: YITAP 2004/11/25
DESCRIPTION				
REV				
A				

QUALITY SYMBOLS
▽=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)	
4 PLACES	± ---
3 PLACES	± ---
2 PLACES	± 0.25
1 PLACE	± 0.25
ANGULAR ± 3 °	
DRAFT WHERE APPLICABLE	
MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE MM ONLY	
DRAWN BY	DATE
DAVID HU	2004/11/05
CHECKED BY	DATE
	2004/11/05
APPROVED BY	DATE
MATERIAL NO.	
SEE NOTES	
SIZE	
A3	

SCALE 4:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
TITLE	USB B TYPE CONNECTOR WITH STRAIGHT TAB (LEAD-FREE)	
molex MOLEX INCORPORATED		
DOCUMENT NO. SD-67068-003		SHEET NO. 2
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



NOTES :
1. MATERIAL :
HOUSING : (a) HIGH TEMP. NYLON, GLASS FIBER FILLED, UL94V-0, COLOR: BLACK,

TERMINAL : PHOSPHOR BRONZE
METAL SHELL : COPPER ALLOY

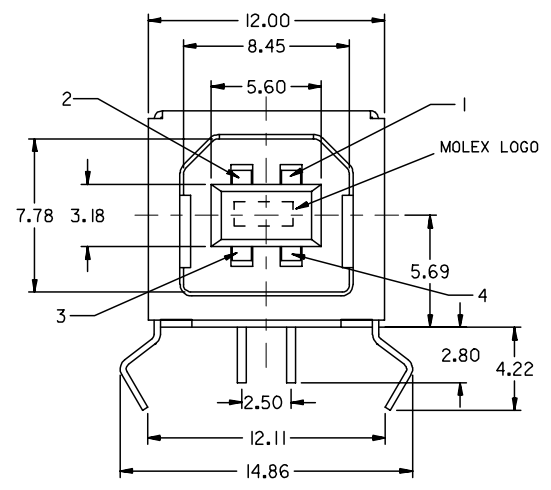
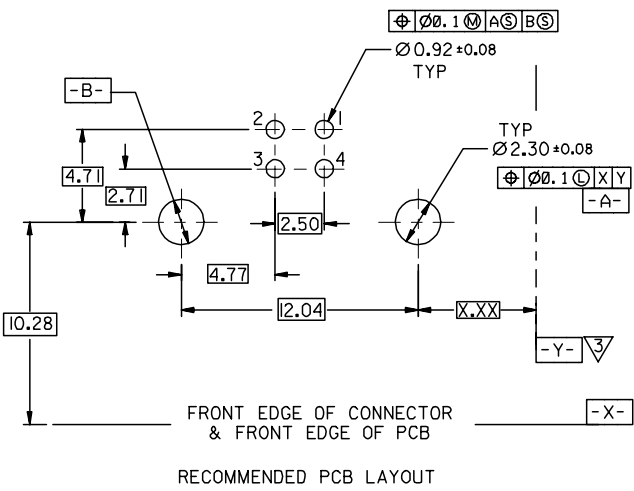
2. PLATING :
TERMINAL :
CONTACT AREA : (a) GOLD FLASH.
(b) GLOD (Au), THICKNESS = 30 MICROINCH MINIMUM.
/0.76 MICROMETER MINIMUM.

SOLDER TAIL :
PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM .
/1.9 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.
/1.27 MICROMETER MINIMUM.

METAL SHELL :
PURE TIN(SN), THICKNESS= 50 MICROINCH MINIMUM.
/1.27 MICROMETER MINIMUM.

4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000



PART NUMBER LEGEND:

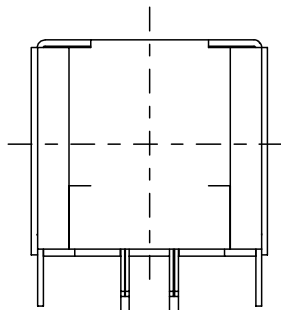
67068- 7041

						MATERIAL : SEE NOTES	 MOLEX TAIWAN LTD. SHEET 3 OF 4	
						FINISH : SEE NOTES		
						WIRE RANGE :		
						INS. RANGE :		
A	NEW RELEASE FOR LEAD-FREE			DAVID HU	2004/11/5	ENG. NO.:	SD-67068-003	REV A
LTR	REVISION RECORD	ECN	DR	DATE	DRAWN BY 2004/11/5 DAVID HU	CHK'D BY	TITLE : HIGH TEMP./USB B TYPE CONNECTOR KINK TYPE BOARD LOCK (LEAD-FREE)	
REVISE ONLY ON CAD SYSTEM						APPR'D BY	SCALE	4 : 1

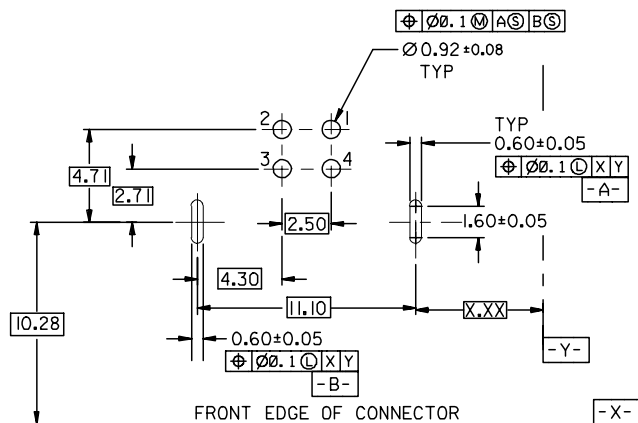
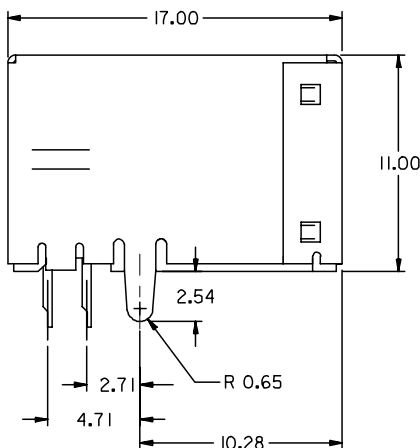
DO NOT SCALE DRAWING

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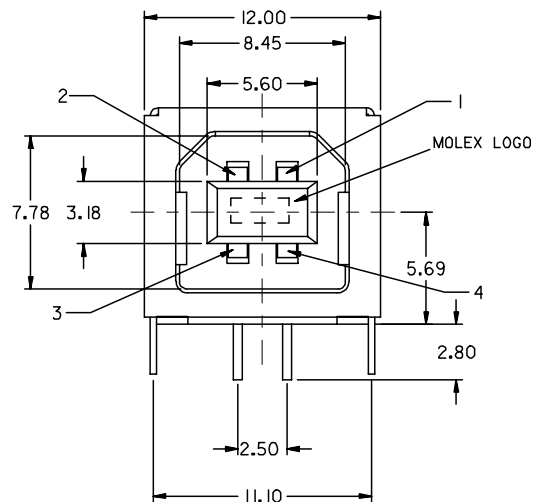
4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000



67068- 7051



RECOMMENDED PCB LAYOUT



						MATERIAL :	SEE NOTES		 MOLEX TAIWAN LTD. SHEET 4 OF 4	
						FINISH :	SEE NOTES			
						WIRE RANGE :				
						INS. RANGE :				
A	NEW RELEASE FOR LEAD-FREE			DAVID HU	2004/11/5	ENG. NO.:			SD-67068-003	REV A
LTR	REVISION RECORD	ECN	DR	DATE	DRAWN BY 2004/11/5 DAVID HU	CHK'D BY		TITLE : HIGH TEMP./USB B TYPE CONNECTOR WITH STRAIGHT TAB (LEAD-FREE)		
REVISE ONLY ON CAD SYSTEM					APPR'D BY		SCALE 4 : 1			

NOTES:

1.MATERIAL:

HOUSING:

- (a)HIGH TEMP,NYLON,GLASS FIBRE FILLED,UL94V-0,COLOR: 88BLACK
- (b)POLYESTER(PBT),30% GLASS FIBER FILLED,UL94V-0,COLOR: 9:WHITE
- TERMINAL: PHOSPHOR BRONZE
- METAL SHELL: COPPER ALLOY

2.PLATING:

TERMINAL:

- (c)GOLD FLASH ON CONTACT AREA,75 MICROINCH MINIMUM PURE TIN(Sn) ON SOLDER TAIL,UNDER 50 MICROINCH MINIMUM NICKEL(Ni) PLATE.
- (d)30 MICROINCH MINIMUM GOLD(Au) ON CONTACT AREA,75 MICROINCH MINIMUM PURE TIN(Sn) ON SOLDER TAIL,UNDER 50 MICROINCH MINIMUM NICKEL(Ni) PLATE.
- (e)GOLD FLASH ON CONTACT AREA,75 MICROINCH MINIMUM MATTE TIN(Sn) ON SOLDER TAIL,UNDER 50 MICROINCH MINIMUM NICKEL(Ni) PLATE.
- (f)30 MICROINCH MINIMUM GOLD(Au) ON CONTACT AREA,75 MICROINCH MINIMUM MATTE TIN(Sn) ON SOLDER TAIL,UNDER 50 MICROINCH MINIMUM NICKEL(Ni) PLATE.

METAL SHELL:

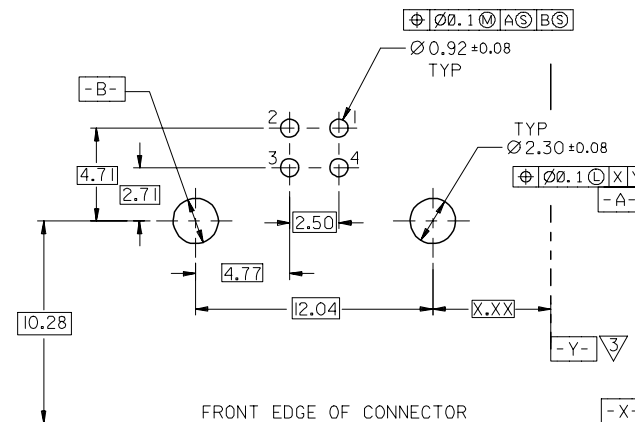
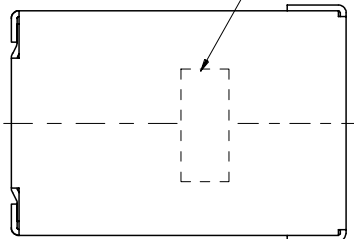
- (g)50 MICROINCH MINIMUM PURE TIN(Sn),UNDER 50 MICROINCH MINIMUM NICKEL(Ni) PLATE.
- (h)50 MICROINCH MINIMUM MATTE TIN(Sn),UNDER 50 MICROINCH MINIMUM NICKEL(Ni) PLATE.

3.DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER.

RECOMMENDED PCB THICKNESS : 1.60±0.05

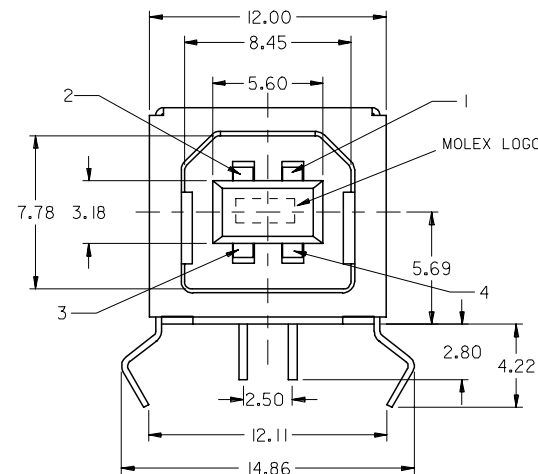
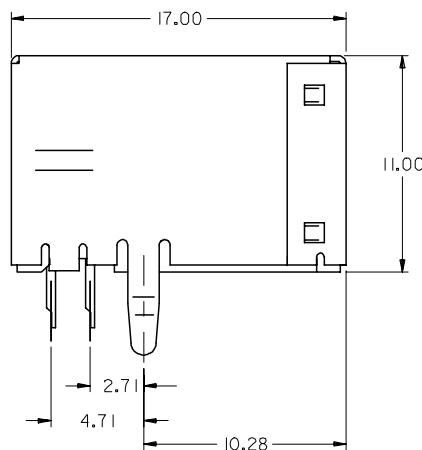
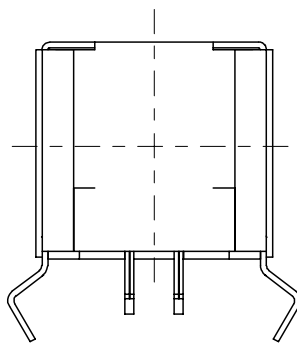
4.PRODUCT SPECIFICATION : REFER TO PS-67998-0000

MOLEX ID OF MFG PLANT CODE



FRONT EDGE OF CONNECTOR & FRONT EDGE OF PCB

RECOMMENDED PCB LAYOUT



P/N	HOUSING COLOR	PLATING
67068-8000	BLACK	GOLD FLASH SEE NOTES[2-(c),2-(g)]
67068-8001	BLACK	30MICROINCH Au SEE NOTES[2-(d),2-(g)]
67068-9000	WHITE	GOLD FLASH SEE NOTES[2-(c),2-(g)]
67068-9001	WHITE	30MICROINCH Au SEE NOTES[2-(d),2-(g)]
67068-8012	BLACK	30MICROINCH Au SEE NOTES[2-(f),2-(h)]
67068-8013	BLACK	GOLD FLASH SEE NOTES[2-(e),2-(h)]

REVISED	EC NO: SH2007-0468	2007/01/19
DRWN:HYE01	CHKD:WANG	2007/01/19
APPR:JNCHEN	2007/01/26	
DESCRIPTION		
REV		

QUALITY SYMBOLS

▽=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.25	± .010
1 PLACE	± 0.25	± .010
ANGULAR	± 3 °	

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY

DRAWN BY	DATE
DAVID HU	2004/11/05
CHECKED BY	DATE
HARVEY	2004/11/05
APPROVED BY	DATE

SEE NOTES

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

SCALE
4:1

DESIGN UNITS
METRIC

THIRD ANGLE
PROJECTION

USB B TYPE CONNECTOR
LEAD-FREE

MOLEX MOLEX INCORPORATED

DOCUMENT NO. SD-67068-004

SHEET NO.
1 OF 1



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.